

### **General Description**

The MAX4249-MAX4257 low-noise, low-distortion operational amplifiers offer Rail-to-Rail® outputs and singlesupply operation down to 2.4V. They draw 400µA of quiescent supply current per amplifier while featuring ultra-low distortion (0.0002% THD), as well as low input voltage noise density (7.9nv/\(\sqrt{Hz}\)) and low input current noise density (0.5fA/ $\sqrt{\text{Hz}}$ ). These features make the devices an ideal choice for portable/battery-powered applications that require low distortion and/or low noise.

For additional power conservation, the MAX4249/4251/ 4253/4256 offer a low-power shutdown mode that reduces supply current to 0.5µA and puts the amplifiers' outputs into a high-impedance state. The MAX4249-MAX4257's outputs swing rail-to-rail and their input common-mode voltage range includes ground. The MAX4250-MAX4254 are unity-gain stable with a gain-bandwidth product of 3MHz. The MAX4249/ MAX4255/MAX4256/MAX4257 are internally compensated for gains of +10V/V or greater with a gain-bandwidth product of 22MHz. The single MAX4250/ MAX4255 are available in space-saving, 5-pin SOT23 packages. The MAX4252 is available in an 8-pin UCSP package and the MAX4253 is available in a 10-pin UCSP package.

### **Applications**

Wireless Communications Devices

PA Control

Portable/Battery-Powered Equipment

Medical Instrumentation

**ADC Buffers** 

Digital Scales/Strain Gauges

Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd. UCSP is a trademark of Maxim Integrated Products, Inc.

### **Features**

- Available in Space-Saving UCSP™, SOT23, and µMAX Packages
- ♦ Low Distortion: 0.0002% THD (1kΩ load)
- ♦ 400µA Quiescent Supply Current per Amplifier
- ♦ Single-Supply Operation from +2.4V to +5.5V
- ◆ Input Common-Mode Voltage Range Includes Ground
- ♦ Outputs Swing Within 8mV of Rails with a  $10k\Omega$
- **♦ 3MHz GBW Product, Unity-Gain Stable** (MAX4250-MAX4254)

22MHz GBW Product, Stable with A<sub>V</sub> ≥ 10V/V (MAX4249/MAX4255/MAX4256/MAX4257)

**♦ Excellent DC Characteristics** 

 $V_{OS} = 70 \mu V$ 

IBIAS = 1pA

Large-Signal Voltage Gain = 116dB

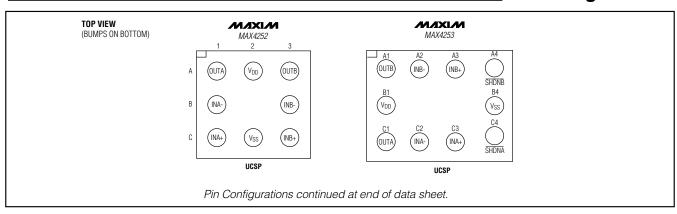
- **♦ Low-Power Shutdown Mode:** Reduces Supply Current to 0.5µA Places Outputs in a High-Impedance State
- **♦ 400pF Capacitive-Load Handling Capability**

### **Ordering Information**

PART	TEMP. RANGE	PIN/BUMP- PACKAGE	TOP MARK
MAX4249ESD	-40°C to +85°C	14 SO	_
MAX4249EUB	-40°C to +85°C	10 μMAX	_
MAX4250EUK-T	-40°C to +85°C	5 SOT23-5	ACCI

Ordering Information continued at end of data sheet. Selector Guide appears at end of data sheet.

### **Pin Configurations**



Maxim Integrated Products 1

#### **ABSOLUTE MAXIMUM RATINGS**

Power-Supply Voltage ( $V_{DD}$ to $V_{SS}$ )+6.0V to -0.3V Analog Input Voltage ( $I_{N-+}$ , $I_{N}$ )( $V_{DD}$ + 0.3V) to ( $V_{SS}$ - 0.3V) SHDN Input Voltage+6.0V to ( $V_{SS}$ - 0.3V) Output Short-Circuit Duration to Either SupplyContinuous Continuous Power Dissipation ( $I_{A}$ = +70°C)
5-Pin SOT23 (derate 7.1mW/°C above +70°C)571mW
8-Pin µMAX (derate 4.5mW/°C above +70°C)362mW
8-Pin SO (derate 5.88mW/°C above +70°C)471mW
8-Pin UCSP (derate 4.7mW/°C above +70°C)379mW
10-Pin UCSP (derate 6.1mW/°C above +70°C)484mW

10-Pin µMAX (derate 5.6mW/°C above +	70°C)444mW
14-Pin SO (derate 8.33mW/°C above +70	0°C)667mW
Operating Temperature Range	40°C to +125°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Bump Temperature (soldering) (Note 1)	
Infrared (15s)	+220°C
Vapor Phase (60s)	+215°C

**Note 1:** This device is constructed using a unique set of packaging techniques that impose a limit on the thermal profile the device can be exposed to during board-level solder attach and rework. This limit permits only the use of the solder profiles recommended in the industry-standard specification, JEDEC 020A, paragrah 7.6, Table 3 for IR/VPR and Convection Reflow. Preheating is required. Hand or wave soldering is not allowed.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **ELECTRICAL CHARACTERISTICS**

 $(V_{DD} = +5V, V_{SS} = 0, V_{CM} = 0, V_{OUT} = V_{DD}/2, R_L \text{ tied to } V_{DD}/2, \overline{SHDN} = V_{DD}, T_A = -40^{\circ}C \text{ to } +125^{\circ}C, \text{ unless otherwise noted.}$  Typical values are at  $T_A = +25^{\circ}C$ .) (Notes 2, 3)

PARAMETER	SYMBOL	C	ONDITION	IS	MIN	TYP	MAX	UNITS
Supply Voltage Range	V <sub>DD</sub>	(Note 4)			2.4		5.5	V
			V <sub>DD</sub> = +3	3V		400		
Quiescent Supply Current per	la la	Normal mode	V <sub>DD</sub> = +	ōV		420	575	
Amplifier	IQ		V <sub>DD</sub> = +	5V, UCSP only		420	655	μΑ
		Shutdown mode	e ( <del>SHDN</del> =	V <sub>SS</sub> ) (Note 2)		0.5	1.5	
Input Offset Voltage (Note 5)	Vos					±0.07	±0.75	mV
Input Offset Voltage Tempco	TCVOS					0.3		μV/°C
Input Bias Current	IB	(Note 6)	(Note 6)			±1	±100	рА
Input Offset Current	los	(Note 6)	(Note 6)			±1	±100	рА
Differential Input Resistance	R <sub>IN</sub>					1000		$G\Omega$
Input Common-Mode Voltage Range	V <sub>CM</sub>	Guaranteed by	CMRR Tes	t	-0.2		V <sub>DD</sub> - 1.1	V
Common-Mode Rejection Ratio	CMRR	V <sub>SS</sub> - 0.2V ≤ V <sub>C</sub>	M ≤ V <sub>DD</sub> -	1.1V	70	115		dB
Power-Supply Rejection Ratio	PSRR	$V_{DD} = 2.4 \text{ to } 5.5$	ōV		75	100		dB
Large Cinnal Walks on Onio			$R_L = 10k\Omega$ to $V_{DD}/2$ ; $V_{OUT} = 25mV$ to $V_{DD} - 4.97V$		80	116		٩D
Large-Signal Voltage Gain	Av	$R_L = 1k\Omega$ to $V_{DD}/2$ ; $V_{OUT} = 150V$ to $V_{DD}$ - 4.75V		80	112		dB	
Output Voltage Swing	Vout	$ V_{IN+} - V_{IN-}  \ge 10$ $R_L = 10k\Omega$ to $V_I$		V <sub>DD</sub> – V <sub>OH</sub> V <sub>OL</sub> - V <sub>SS</sub>		8 7	25 20	mV

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{DD}=+5V,\,V_{SS}=0,\,V_{CM}=0,\,V_{OUT}=V_{DD}/2,\,R_L\,\,\text{tied to}\,\,V_{DD}/2,\,\overline{SHDN}=V_{DD},\,T_A=-40^{\circ}C\,\,\text{to}\,\,+125^{\circ}C,\,\text{unless otherwise noted}.\,\,\text{Typical values are at}\,\,T_A=+25^{\circ}C)\,\,(\text{Notes}\,\,2,\,3)$ 

PARAMETER	SYMBOL	CONDITION	NS	MIN	TYP	MAX	UNITS	
Output Valtage Swins	Va:	$ V_{IN+} - V_{IN-}  \ge 10 \text{mV},$	V <sub>DD</sub> – V <sub>OH</sub>		77	200	mV	
Output Voltage Swing	Vout	$R_L = 1k\Omega$ to $V_{DD}/2$	V <sub>OL</sub> - V <sub>SS</sub>		47	100	IIIV	
Output Short-Circuit Current	Isc				68		mA	
Output Leakage Current	ILEAK	Shutdown mode (SHDN = VOUT = VSS to VDD (Note			0.001	1.0	μΑ	
SHDN Logic Low	VIL	(Note 2)				0.2 X V <sub>DD</sub>	V	
SHDN Logic High	V <sub>IH</sub>	(Note 2)		0.8 x V <sub>DD</sub>			V	
SHDN Input Current	I <sub>IL</sub> /I <sub>IH</sub>	SHDN = V <sub>SS</sub> = V <sub>DD</sub> (Note	: 2)		0.5	1.5	μΑ	
Input Capacitance					11		рF	
Cain Dandwidth Dradwat	CDW	MAX4250-MAX4254			3		N 41 1-	
Gain Bandwidth Product	GBW	MAX4249/MAX4255/MAX4	1256/MAX4257		22		MHz	
Olavi Data	OD	MAX4250-MAX4254			0.3		\ //·	
Slew Rate	SR	MAX4249/MAX4255/MAX4	1256/MAX4257	2.1			V/µs	
Peak-to-Peak Input Noise Voltage	e <sub>n</sub> (p-p)	f = 0.1Hz to 10Hz			760		nVp-p	
		f = 10Hz			2.7			
Input Voltage Noise Density	en	f = 1kHz		8.9		nV/√F		
		f = 30kHz			7.9			
Input Current Noise Density	in	f = 1kHz			0.5		fA/√H	
		MAX4250-MAX4254 A <sub>V</sub> = +1V/V, V <sub>OUT</sub> =	f = 1kHz		0.0004			
Total Harmonic Distortion Plus		2Vp-p, R <sub>L</sub> = $1k\Omega$ to GND (Note 7)	f = 20kHz		0.006			
Noise	THD+N	MAX4249/MAX4255/ MAX4256/MAX4257	f = 1kHz		0.0012		%	
		$A_V = +1V/V$ , $V_{OUT} = 2V_{p-p}$ , $R_L = 1k\Omega$ to GND (Note 7)	f = 20kHz	0.007				
Capacitive-Load Stability		No sustained oscillations			400		рF	
		MAX4250-MAX4254, A <sub>V</sub> =	= +1V/V		10			
Gain Margin	GM	MAX4249/MAX4255/MAX4 A <sub>V</sub> = +10V/V	MAX4249/MAX4255/MAX4256/MAX4257,		12.5		dB	
		MAX4250-MAX4254, A <sub>V</sub> =	= +1V/V		74			
Phase Margin	ΦМ	MAX4249/MAX4255/MAX $_{V} = +10V/V$	1256/MAX4257,		68		degre	

### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{DD}=+5V,\,V_{SS}=0,\,V_{CM}=0,\,V_{OUT}=V_{DD}/2,\,R_L\,\,tied\,\,to\,\,V_{DD}/2,\,\overline{SHDN}=V_{DD},\,T_A=-40^{\circ}C\,\,to\,\,+125^{\circ}C,\,unless\,\,otherwise\,\,noted.\,\,Typical\,\,values\,\,are\,\,at\,\,T_A=+25^{\circ}C)\,\,(Notes\,2,\,3)$ 

PARAMETER	SYMBOL	СО	NDITIONS	MIN	TYP	MAX	UNITS
			MAX4250-MAX4254		6.7		
Settling Time		To 0.01%, Vout = 2V step	MAX4249/MAX4255/ MAX4256/MAX4257		1.6		μs
	t <sub>SH</sub> nor	IVDD = 5% of normal operation	MAX4251/MAX4253		0.8		
Delay Time to Shutdown			MAX4249/MAX4256		1.2		μs
		VOUT = 2.5V, VOUT settles to	MAX4251/MAX4253		8		μs
Donay Time to Emails	'EIN	0.1%	MAX4249/MAX4256		3.5		μο
Power-Up Delay Time	tpu	V <sub>DD</sub> = 0 to 5V ste	p, Vout stable to 0.1%		6		μs

Note 2: SHDN is available on the MAX4249/MAX4251/MAX4253/MAX4256 only.

Note 3: All device specifications are 100% tested at  $T_A = +25^{\circ}C$ . Limits over temperature are guaranteed by design.

Note 4: Guaranteed by the PSRR test.

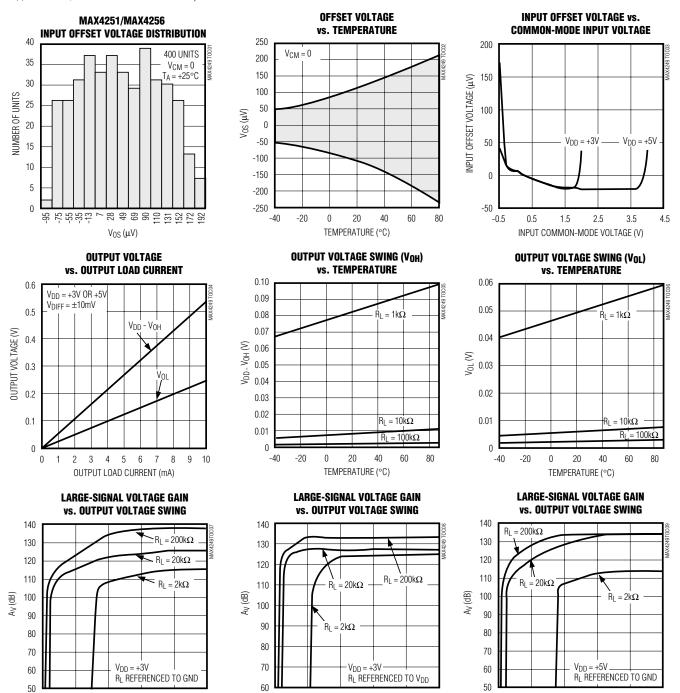
Note 5: Offset voltage prior to reflow on UCSP.

Note 6: Guaranteed by design.

Note 7: Lowpass-filter bandwidth is 22kHz for f = 1kHz and 80kHz for f = 20kHz. Noise floor of test equipment = 10nV/√Hz.

### Typical Operating Characteristics

 $(V_{DD} = +5V, V_{SS} = 0, V_{CM} = V_{OUT} = V_{DD}/2$ , input noise floor of test equipment =10nV/ $\sqrt{\text{Hz}}$  for all distortion measurements,  $T_A = +25^{\circ}\text{C}$ , unless otherwise noted.)



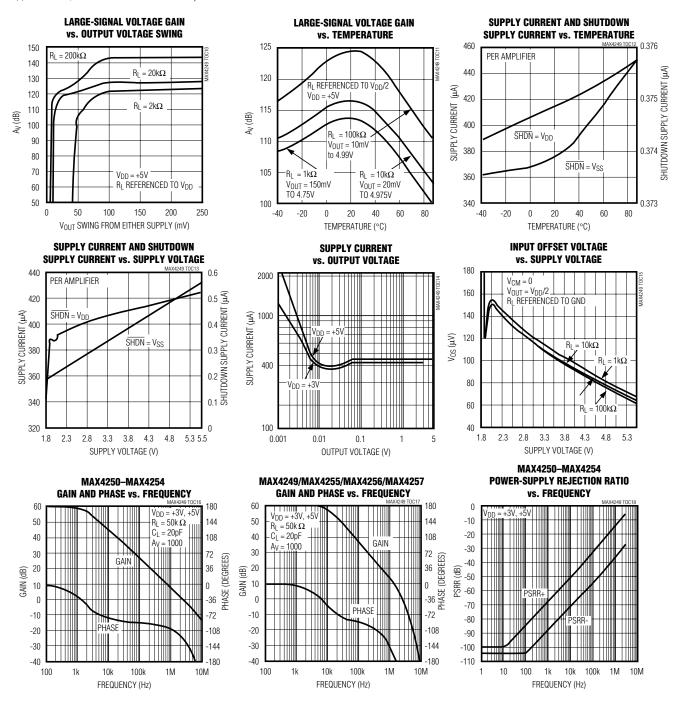
V<sub>OUT</sub> SWING FROM EITHER SUPPLY (mV)

V<sub>OUT</sub> SWING FROM EITHER SUPPLY (mV)

V<sub>OUT</sub> SWING FROM EITHER SUPPLY (mV)

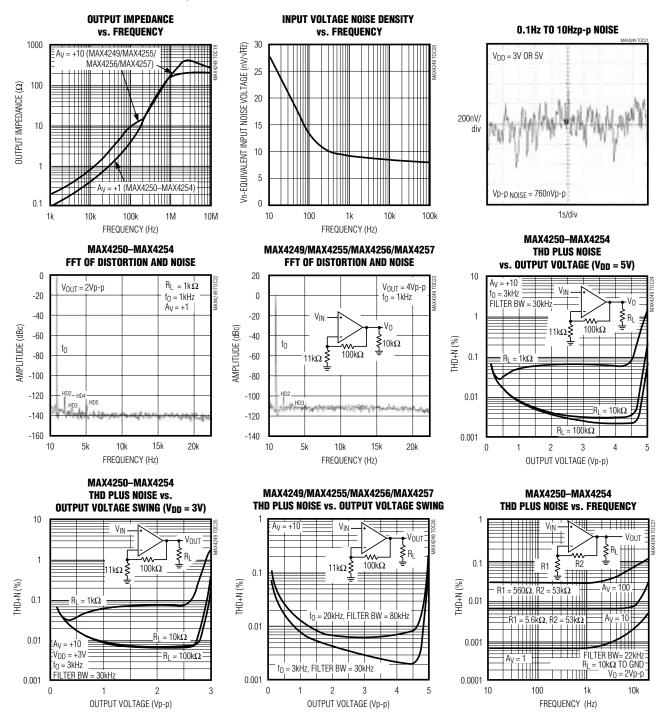
### Typical Operating Characteristics (continued)

 $(V_{DD} = +5V, V_{SS} = 0, V_{CM} = V_{OUT} = V_{DD}/2$ , input noise floor of test equipment = 10nV/ $\sqrt{Hz}$  for all distortion measurements,  $T_A = +25$ °C, unless otherwise noted.)



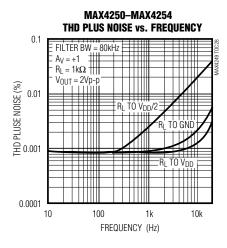
### Typical Operating Characteristics (continued)

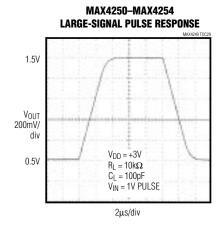
 $(V_{DD} = +5V, V_{SS} = 0, V_{CM} = V_{ODT} = V_{DD}/2$ , input noise floor of test equipment =10nV/ $\sqrt{Hz}$  for all distortion measurements,  $T_A = +25^{\circ}C$ , unless otherwise noted.)

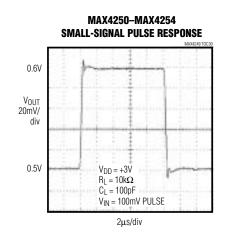


### \_Typical Operating Characteristics (continued)

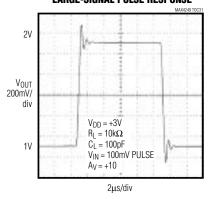
 $(V_{DD} = +5V, V_{SS} = 0, V_{CM} = V_{ODT} = V_{DD}/2$ , input noise floor of test equipment = 10nV/ $\sqrt{Hz}$  for all distortion measurements,  $T_A = +25^{\circ}C$ , unless otherwise noted.)



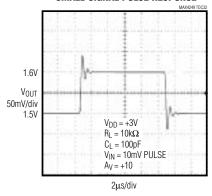


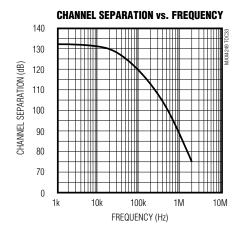


#### MAX4249/MAX4255/MAX4256/MAX4257 Large-Signal Pulse Response



#### MAX4249/MAX4255/MAX4256/MAX4257 SMALL-SIGNAL PULSE RESPONSE





### **Pin Description**

			PIN						
MAX4250/ MAX4255	MAX4251/ MAX4256	MAX4252/ MAX4257	MAX4252	MAX4249/ MAX4253		MAX4254	NAME	FUNCTION	
5 SOT23	8 SO/ μMAX	8 SO/ μMAX	8 UCSP	10 UCSP	10 μMAX	14 SO	14 SO		
1	6	1, 7	A1, A3	A1, C1	1, 9	1, 13	1, 7, 8, 14	OUT, OUTA, OUTB, OUTC, OUTD	Amplifier Output
2	4	4	C2	B4	4	4	11	Vss	Negative Supply. Connect to ground for single-supply operation
3	3	3, 5	C1, C3	A3, C3	3, 5	3, 11	3, 5, 10, 12	IN+, INA+, INB+, INC+, IND+	Noninverting Amplifier Input
4	2	2, 6	B1, B3	A2, C2	2, 6	2, 12	2, 6, 9, 13	IN-, INA-, INB-, INC-, IND-	Inverting Amplifier Input
5	7	8	A2	B1	8	14	4	V <sub>DD</sub>	Positive Supply
_	8	_	-	A4, C4	_	5, 9	_	SHDN, SHDNA, SHDNB	Shutdown Input, Connect to V <sub>DD</sub> or leave unconnected for normal operation (amplifier(s) enabled).
_	1, 5	_	_			5, 7, 8, 10	_	N.C.	No Connection. Not internally connected.
_	_	_	B2	B2, B3	_	_	_	_	Not populated with solder sphere

### **Detailed Description**

The MAX4249–MAX4257 single-supply operational amplifiers feature ultra-low noise and distortion while consuming very little power. Their low distortion and low noise make them ideal for use as preamplifiers in wide dynamic-range applications, such as 16-bit analog-to-digital converters (see *Typical Operating Circuit*). Their high-input impedance and low noise are also useful for signal conditioning of high-impedance sources, such as piezoelectric transducers.

These devices have true rail-to-rail ouput operation, drive loads as low as  $1k\Omega$  while maintining DC accuracy, and can drive capactive loads up to 400pF without

oscillation. The input common-mode voltage range extends from  $V_{DD}$  - 1.1V to 200mV beyond the negative rail. The push/pull output stage maintains excellent DC characteristics, while delivering up to  $\pm 5$ mA of current.

The MAX4250–4254 are unity-gain stable, whereas, the MAX4249/MAX4255/MAX4256/MAX4257 have a higher slew rate and are stable for gains  $\geq$  10V/V. The MAX4249/MAX4251/MAX4253/MAX4256 feature a low-power shutdown mode, which reduces the supply current to 0.5µA and disables the outputs.

#### **Low Distortion**

Many factors can affect the noise and distortion that the device contributes to the input signal. The following

guidelines offer valuable information on the impact of design choices on Total Harmonic Distortion (THD).

Choosing proper feedback and gain resistor values for a particular application can be a very important factor in reducing THD. In general, the smaller the closed-loop gain, the smaller the THD generated, especially when driving heavy resistive loads. Large-value feedback resistors can significantly improve distortion. The THD of the part normally increases at approximately 20dB per decade, as a function of frequency. Operating the device near or above the full-power bandwidth significantly degrades distortion.

Referencing the load to either supply also improves the part's distortion performance, because only one of the MOSFETs of the push/pull output stage drives the output. Referencing the load to mid-supply increases the part's distortion for a given load and feedback setting. (See the Total Harmonic Distortion vs. Frequency graph in the *Typical Operating Characteristics*.)

For gains ≥ 10V/V, the decompensated devices MAX4249/MAX4255/MAX4256/MAX4257 deliver the best distortion performance, since they have a higher slew rate and provide a higher amount of loop gain for a given closed-loop gain setting. Capacitive loads below 400pF, do not significantly affect distortion results. Distortion performance remains relatively constant over supply voltages.

### **Low Noise**

The amplifier's input-referred noise voltage density is dominated by flicker noise at lower frequencies, and by thermal noise at higher frequencies. Because the thermal noise contribution is affected by the parallel combination of the feedback resistive network (RF II RG, Figure 1), these resistors should be reduced in cases where the system bandwidth is large and thermal noise is dominant. This noise contribution factor decreases, however, with increasing gain settings.

For example, the input noise voltage density of the circuit with  $R_F=100k\Omega,\ R_G=11k\Omega$  (Av = 10V/V) is  $e_{\Pi}=15nV/\sqrt{Hz},\ e_{\Pi}$  can be reduced to  $9nV/\sqrt{Hz}$  by choosing  $R_F=10k\Omega,\ R_G=1.1k\Omega$  (Av = 10V/V), at the expense of greater current consumption and potentially higher distortion. For a gain of 100V/V with  $R_F=100k\Omega,\ R_G=1.1k\Omega,$  the  $e_{\Pi}$  is low  $(9nV/\sqrt{Hz}).$ 

## Using a Feed-Forward Compensation Capacitor, Cz

The amplifier's input capacitance is 11pF. If the resistance seen by the inverting input is large (feedback network), this can introduce a pole within the amplifier's bandwidth, resulting in reduced phase margin.

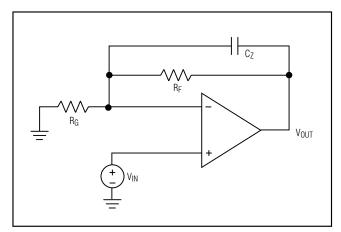


Figure 1. Adding Feed-Forward Compensation

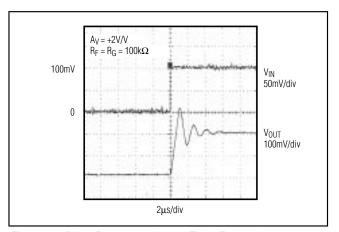


Figure 2a. Pulse Response with No Feed-Forward Compensation

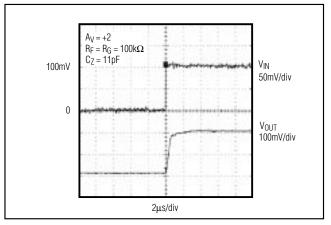


Figure 2b. Pulse Response with 10pF Feed-Forward Compensation

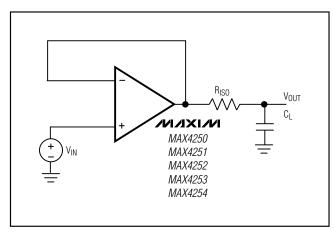


Figure 3. Overdriven Input Showing No Phase Reversal

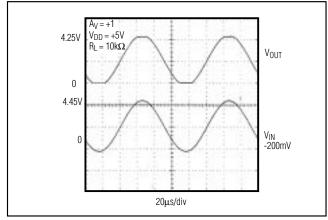


Figure 4. Rail-to-Rail Output Operation

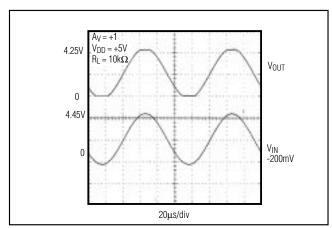


Figure 5. Capacitive-Load Driving Circuit

Compensate the reduced phase margin by introducing a feed-forward capacitor (Cz) between the inverting input and the output (Figure 1). This effectively cancels the pole from the inverting input of the amplifier. Choose the value of Cz as follows:

$$C_Z = 11 \times (R_F / R_G) [pF]$$

In the unity-gain stable MAX4250–MAX4254, the use of a proper Cz is most important for Av = +2V/V, and Av = -1V/V. In the decompensated MAX4249/MAX4255/ MAX4256/MAX4257, Cz is most important for Av = +10V/V. Figures 2a and 2b show transient response both with and without Cz.

Using a slightly smaller Cz than suggested by the formula above achieves a higher bandwidth at the expense of reduced phase and gain margin. As a general guideline, consider using Cz for cases where Rg II RF is greater than 20k $\Omega$  (MAX4250–MAX4254) or greater than 5k $\Omega$  (MAX4249/MAX4255/MAX4256/MAX4257).

### \_Applications Information

The MAX4249–MAX4257 combine good driving capability with ground-sensing input and rail-to-rail output operation. With their low distortion, low noise and low-power consumption, these devices are ideal for use in portable instrumentation systems and other low-power, noise-sensitive applications.

#### Ground-Sensing and Rail-to-Rail Outputs

The common-mode input range of these devices extends below ground, and offers excellent common-mode rejection. These devices are guaranteed not to undergo phase reversal when the input is overdriven (Figure 3).

Figure 4 showcases the true rail-to-rail output operation of the amplifier, configured with AV = 10V/V. The output swings to within 8mV of the supplies with a  $10k\Omega$  load, making the devices ideal in low-supply-voltage applications.

### **Output Loading and Stability**

Even with their low quiescent current of 400 $\mu$ A, these amplifiers can drive 1k $\Omega$  loads while maintaining excellent DC accuracy. Stability while driving heavy capacitive loads is another key feature.

These devices maintain stability while driving loads up to 400pF. To drive higher capacitive loads, place a small isolation resistor in series between the output of the amplifier and the capacitive load (Figure 5). This resistor improves the amplifier's phase margin by isolating the capacitor from the op amp's output.

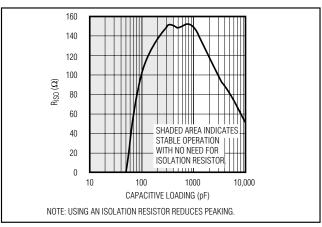


Figure 6. Isolation Resistance vs. Capacitive Loading to Minimize Peaking (<2dB)

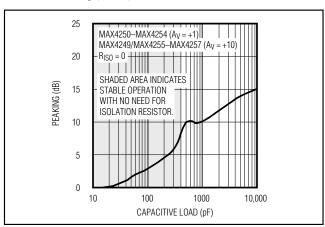


Figure 7. Peaking vs. Capacitive Load

Reference Figure 6 to select a resistance value that will ensure a load capacitance that limits peaking to <2dB (25%). For example, if the capacitive load is 1000pF, the corresponding isolation resistor is 150 $\Omega$ . Figure 7 shows that peaking occurs without the isolation resistor. Figure 8 shows the unity-gain bandwidth vs. capacitive load for the MAX4250–MAX4254.

#### **Power Supplies and Layout**

The MAX4249–MAX4257 operate from a single  $\pm 2.4V$  to  $\pm 5.5V$  power supply or from dual supplies of  $\pm 1.20V$  to  $\pm 2.75V$ . For single-supply operation, bypass the power supply with a  $0.1\mu F$  ceramic capacitor placed close to the  $V_{DD}$  pin. If operating from dual supplies, bypass each supply to ground.

Good layout improves performance by decreasing the amount of stray capacitance and noise at the op amp's inputs and output. To decrease stray capacitance, min-

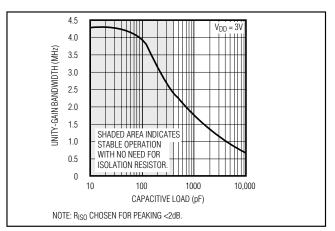


Figure 8. MAX4250-4254 Unity-Gain Bandwidth vs. Capacitive Load

imize PC board trace lengths and resistor leads, and place external components close to the op amp's pins.

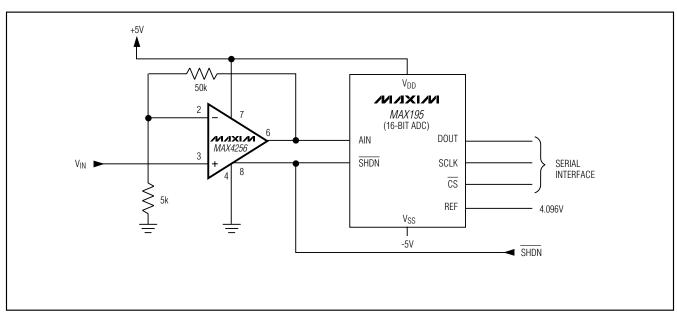
#### **UCSP Package Consideration**

For general UCSP package information and PC layout considerations, please refer to the Maxim Application Note (Wafer-Level Ultra-Chip-Board-Scale-Package).

### **UCSP** Reliability

The chip-scale package (UCSP) represents a unique packaging form factor that may not perform equally to a packaged product through traditional mechanical reliability tests. CSP reliability is integrally linked to the user's assembly methods, circuit board material, and usage environment. The user should closely review these areas when considering use of a CSP package. Performance through Operating Life Test and Moisture Resistance remains uncompromised as it is primarily determined by the wafer-fabrication process. Mechanical stress performance is a greater consideration for a CSP package. CSPs are attached through direct solder contact to the user's PC board, foregoing the inherent stress relief of a packaged product lead frame. Solder joint contact integrity must be considered. Table 1 shows the testing done to characterize the CSP reliability performance. In conclusion, the UCSP is capable of performing reliably through environmental stresses as indicated by the results in the table. Additional usage data and recommendations are detailed in the UCSP application note, which can be found on Maxim's website at www.maxim-ic.com.

### \_Typical Operating Circuit



**Table 1. Reliability Test Data** 

TEST	CONDITIONS	DURATION	NO. OF FAILURES PER SAMPLE SIZE
Temperature Cycle	-35°C to +85°C, -40°C to +100°C	150 cycles, 900 cycles	0/10, 0/200
Operating Life	T <sub>A</sub> = +70°C	240h	0/10
Moisture Resistance	-20°C to +60°C, 90% RH	240h	0/10
Low-Temperature Storage	-20°C	240h	0/10
Low-Temperature Operational	-10°C	24h	0/10
Solderability	8h steam age	_	0/15
ESD	±2000V, Human Body Model	_	0/5
High-Temperature Operating Life	T <sub>J</sub> = +150°C	168h	0/45

### **Selector Guide**

PART	GAIN BANDWIDTH (MHz)	MINIMUM STABLE GAIN (V/V)	NO. OF AMPLIFIERS PER PACKAGE	SHUTDOWN MODE	PIN-PACKAGE
MAX4249	22	10	2	Yes	10-pin μMAX, 14-pin SO
MAX4250	3	1	1		5-pin SOT23
MAX4251	3	1	1	Yes	8-pin μMAX/SO
MAX4252	3	1	2	_	8-pin μMAX/SO, 8-pin UCSP
MAX4253	3	1	2	Yes	10-pin μMAX, 14-pin SO, 10-pin UCSP
MAX4254	3	1	4	_	14-pin SO
MAX4255	22	10	1	_	5-pin SOT23
MAX4256	22	10	1	Yes	8-pin μMAX/SO
MAX4257	22	10	2	_	8-pin μMAX/SO

### Ordering Information (continued)

PART	TEMP. RANGE	PIN/BUMP- PACKAGE	TOP MARK
MAX4251ESA	-40°C to +85°C	8 SO	
MAX4251EUA	-40°C to +85°C	8µMAX	_
MAX4252ESA	-40°C to +85°C	8 SO	_
MAX4252EBA-T*	-40°C to +85°C	8 UCSP	AAO
MAX4252EUA	-40°C to +85°C	8 µMAX	_
MAX4253EUB	-40°C to +85°C	10 μMAX	_
MAX4253EBB-T*	-40°C to +85°C	10 UCSP	AAK
MAX4253ESD	-40°C to +85°C	14 SO	_
MAX4254ESD	-40°C to +85°C	14 SO	_
<b>MAX4255</b> EUK-T	-40°C to +85°C	5 SOT23-5	ACCJ
MAX4256ESA	-40°C to +85°C	8 SO	_
MAX4256EUA	-40°C to +85°C	8 μΜΑΧ	_
MAX4257ESA	-40°C to +85°C	8 SO	_
MAX4257EUA	-40°C to +85°C	8 µMAX	_

<sup>\*</sup>UCSP reliability is integrally linked to the user's assembly methods, circuit board material, and environment. Refer to the UCSP Reliability Notice in the UCSP Reliability section of this data sheet for more information.

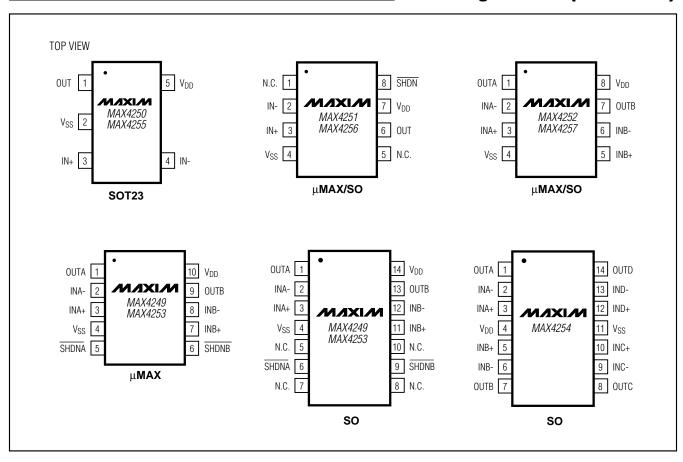
### Chip Information

TRANSISTOR COUNTS:

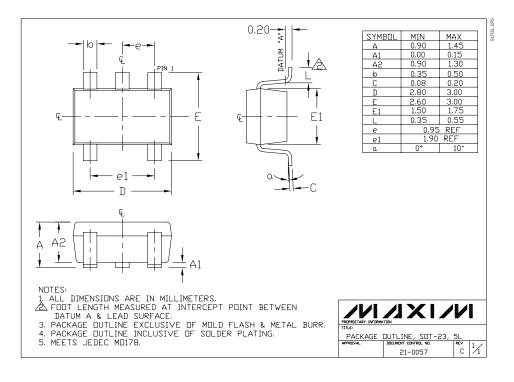
MAX4250/MAX4251/MAX4255/MAX4256: 170 MAX4249/MAX4252/MAX4253/MAX4257: 340

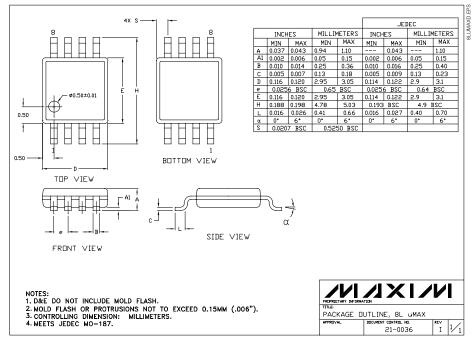
MAX4254: 680

Pin Configurations (continued)

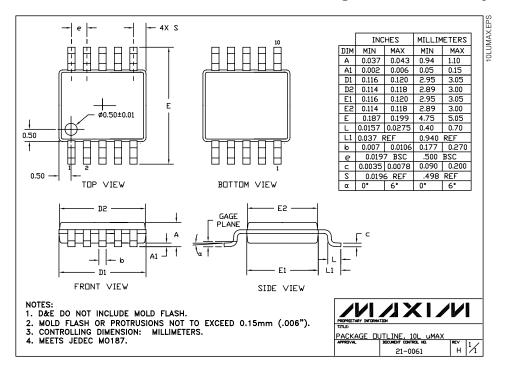


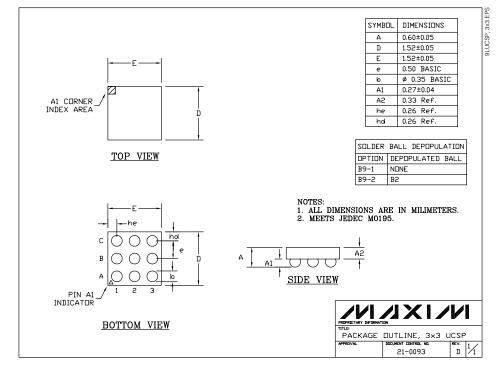
### Package Information



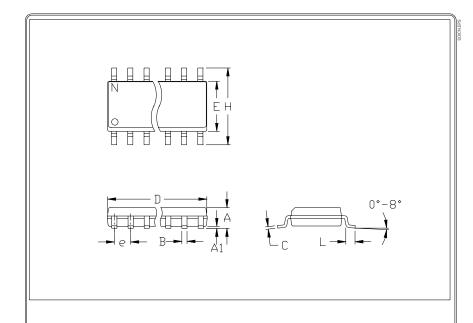


### Package Information (continued)





Package Information (continued)



	INC	HES	MILLIM	IETERS
	MIN	MAX	MIN	MAX
Α	0.053	0.069	1.35	1.75
A1	0.004	0.010	0.10	0.25
В	0.014	0.019	0.35	0.49
С	0.007	0.010	0.19	0.25
6	0.0	)50	1.6	27
E	0.150	0.157	3.80	4.00
Η	0.228	0.244	5.80	6.20
h	0.010	0.020	0.25	0.50
L	0.016	0.050	0.40	1.27
h L	0.010			

		INCHES		MILLIM	ETERS		
		MIN	MAX	MIN	MAX	Ν	MS012
	D	0.189	0.197	4.80	5.00	8	Α
ſ	D	0.337	0.344	8.55	8.75	14	В
	D	0.386	0.394	9.80	10.00	16	С

- NOTES:

  1. D&E DO NOT INCLUDE MOLD FLASH
  2. MDLD FLASH OR PROTRUSIONS NOT
  TO EXCEED .15mm (.006")

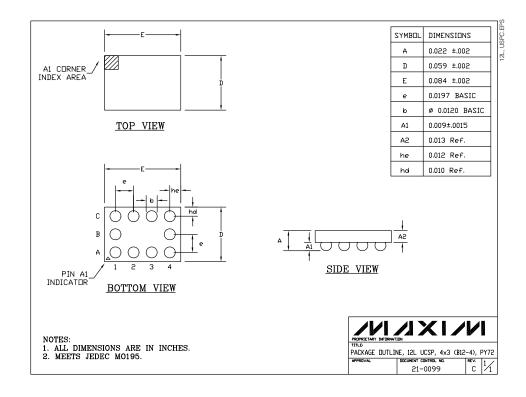
  3. LEADS TO BE COPLANAR WITHIN
  .102mm (.004")

  4. CONTROLLING DIMENSION: MILLIMETER
  5. MEETS JEDEC MS012-XX AS SHOWN
  IN ABOVE TABLE
  6. N = NUMBER OF PINS

PACKAGE FAMILY DUTLINE: SDIC .150"

21-0041 A

### Package Information (continued)



Maxim cannot assume responsibility for use of any circuitry other than circuitry entirely embodied in a Maxim product. No circuit patent licenses are implied. Maxim reserves the right to change the circuitry and specifications without notice at any time.